



Material Content Data Sheet



Sales Product Name		IPD50R3K0CE		Issued		24. January 2018		
MA#		MA001412998						
Package		PG-TO252-3-344		Weight*		321.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.853	0.27	0.27	2653	2653
leadframe	non noble metal	iron	7439-89-6	0.144	0.04		448	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	copper	7440-50-8	143.904	44.76	44.81	447540	448122
wire	non noble metal	aluminium	7429-90-5	1.404	0.44	0.44	4367	4367
encapsulation	organic material	carbon black	1333-86-4	0.685	0.21		2130	
	plastics	epoxy resin	-	18.494	5.75		57515	
	inorganic material	silicondioxide	60676-86-0	117.812	36.64	42.60	366394	426039
leadfinish	non noble metal	tin	7440-31-5	3.881	1.21	1.21	12071	12071
solder	noble metal	silver	7440-22-4	0.032	0.01		100	
	non noble metal	tin	7440-31-5	0.026	0.01		80	
	non noble metal	lead	7439-92-1	1.229	0.38	0.40	3821	4001
heatspreader	non noble metal	iron	7439-89-6	0.033	0.01		103	
	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	copper	7440-50-8	32.995	10.26	10.27	102613	102747
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com